

# SPECIFICATION, WAFER RECLAIM SERVICE

## Incoming Inspection:

1. Upon receipt of material, Noel visually inspects wafers for chips, cracks, film types. Defective wafers will be rejected and returned unprocessed.
2. Wafers are chemically stripped.
3. Wafers are polished.
4. Wafers are cleaned utilizing RCA/SC1/SC2 Process.

## Standard Specifications:

Inspection Criteria	Reject	Accept
Finger Prints	100%	0%
Chips/Cracks	100%	0%
Water Spots/Streaks	100%	0%
Edge Exclusion	≥3mm	≤3mm
Wand Marks	100%	0%
Micro-Scratches	≥1.25 inches in length	≤1.25 inches in length
Resistivity		<1.0Ω/cm, >1.0Ω/cm
Pitting (Depth of removal <6um)	≥3%	≤3%
Wafer Thickness	≤675μm	≥700μm